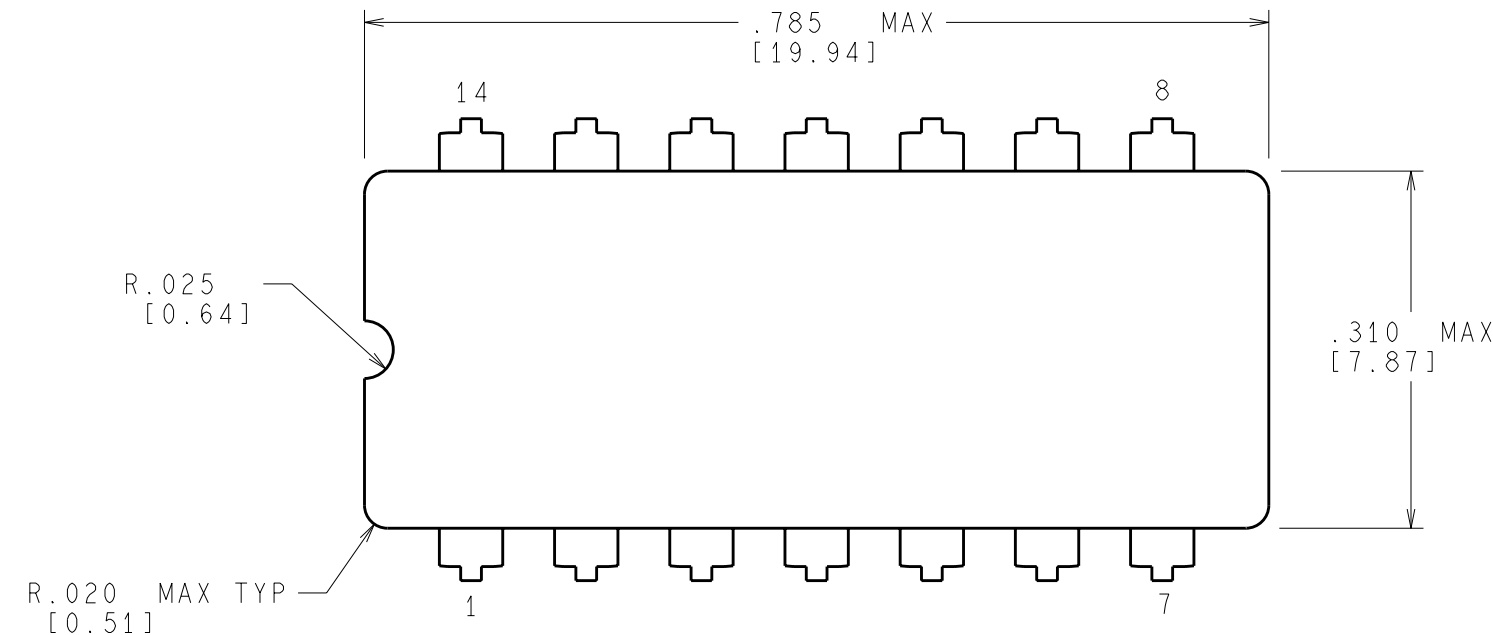
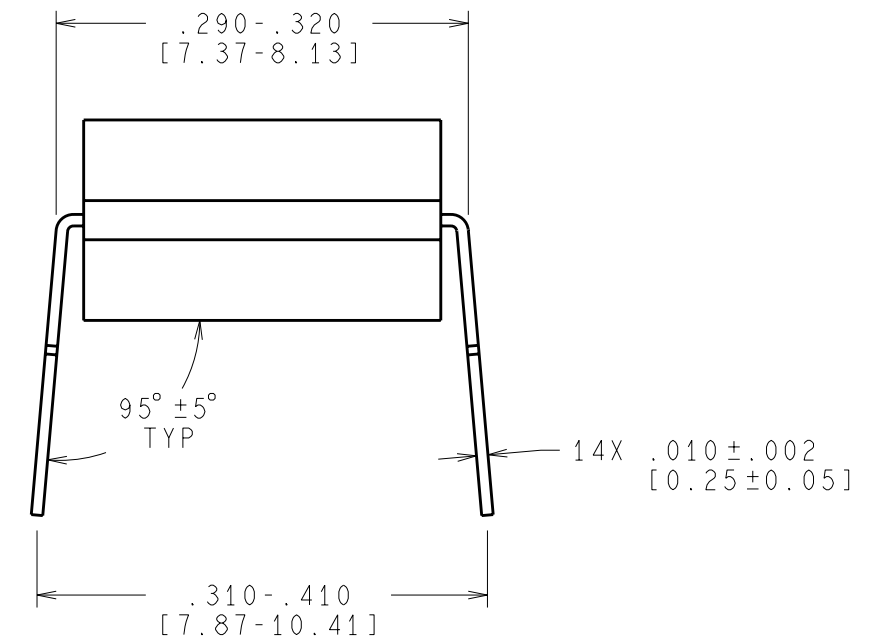
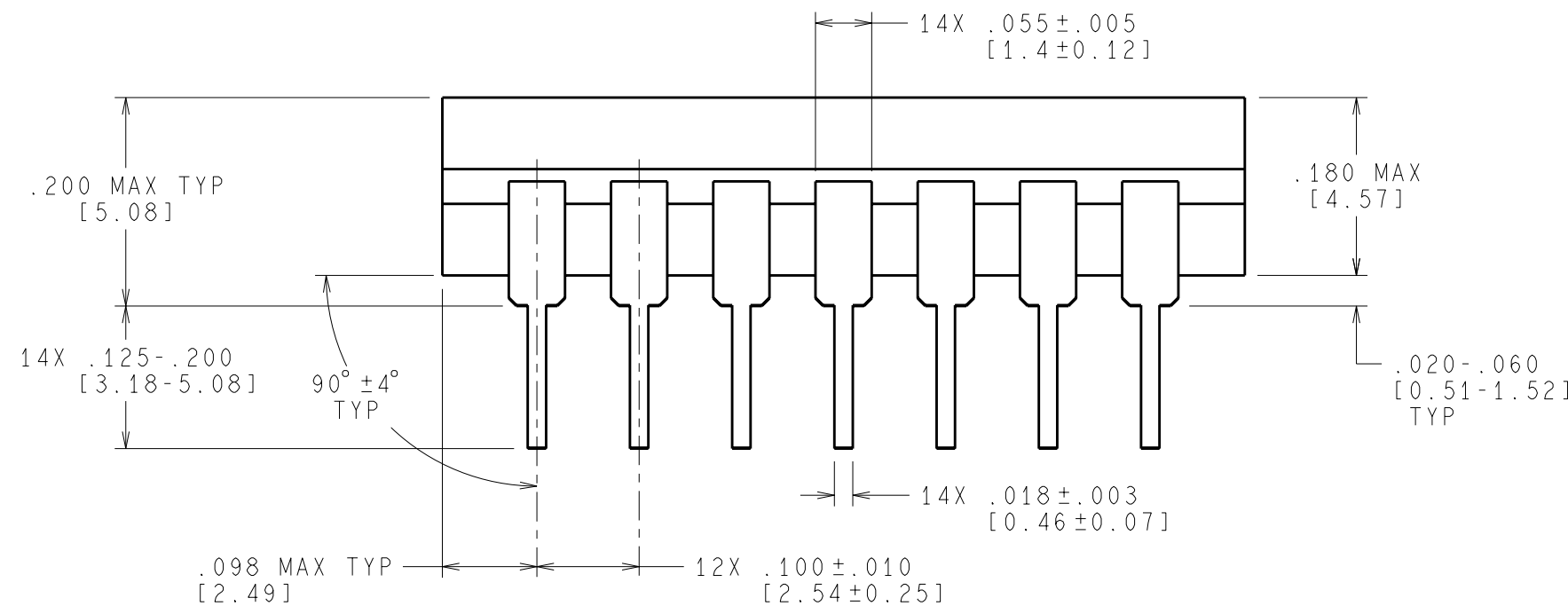


REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
H	REVISE & REDRAW PER CURRENT STD	10001	09/15/1993	TL/SC
J	REVISE & REDRAW PER CURRENT STD; REVISE TITLE	739	07/03/2002	TL/CD



**CONTROLLING DIMENSION IS INCH  
VALUES IN [ ] ARE MILLIMETERS**



NOTES: UNLESS OTHERWISE SPECIFIED

1. LEAD FINISH TO BE ONE OF THE FOLLOWING:
  - a. 200 MICROINCHES [5.08 MICROMETERS] MINIMUM SOLDER MEASURED AT THE CREST OF THE MAJOR FLATS.
  - b. 200 TO 800 MICROINCHES [5.08 TO 10.16 MICROMETERS] TIN PLATE OVER 50 TO 300 MICROINCHES [1.27 TO 7.62 MICROMETERS] NICKEL UNDERPLATE OR BASIS METAL.
  - c. 50 TO 100 MICROINCHES [1.27 TO 2.54 MICROMETERS] GOLD OVER 50 TO 350 MICROINCHES [1.27 TO 8.89 MICROMETERS] NICKEL UNDERPLATE.

2. NO JEDEC REGISTRATION AS OF JULY 2002.

**MIL-STD-1835B  
CONFIGURATION CONTROL**

**MIL-PRF-38535  
CONFIGURATION CONTROL**

APPROVALS	DATE	 2900 Semiconductor Dr., Santa Clara, CA 95052-8090	<b>CERDIP, .785 x .310 BODY, 14 LEAD, .300 CENTERS, .100 PITCH</b>
DRAWN T. LEQUANG	07/03/2002		
DFTG. CHK. MARTA SUCHY	07/03/2002		
ENGR. CHK. CORNEL DEVERA	07/03/2002		
PROJECTION	SCALE	SIZE	DRAWING NUMBER
	NTS	B	(SC)MKT-J14A
	FORMERLY: N/A		SHEET 1 of 1